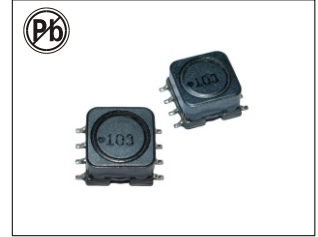


# SHIELDED SMD POWER INDUCTORS

## SB0906 SERIES



### FEATURES:

- Magnetic Shielded Surface Mount Inductor with High Current Rating.
- Low Resistance to Keep Power Loss Minimum.

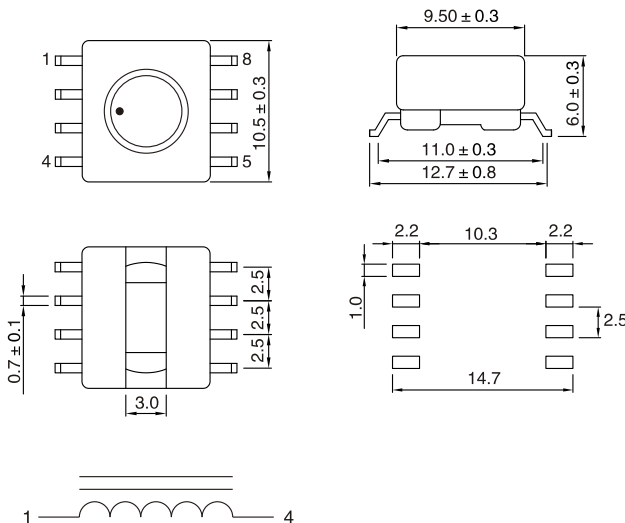
### APPLICATIONS:

- Excellent for Power Line DC-DC Conversion
- Applications used in Hard disk, Notebook Computers and Other Electronic Equipment.

### ELECTRICAL CHARACTERISTICS:

Part Number	Inductance (μH)	Q ref.	Test Freq. (Hz)		SRF (MHz) nom.	DCR (Ω) max.	IDC(A) max.	Part Number	Inductance (μH)	Q ref.	Test Freq. (Hz)		SRF (MHz) nom.	DCR (Ω) max.	IDC(A) max.
			L	Q							L	Q			
SB0906								SB0906							
2R7M	2.70 ± 20%	23	1K	7.96 M	85.00	0.032	3.200	221Y	220.0 ± 15%	40	1K	0.796 M	5.00	1.000	0.480
3R5M	3.50 ± 20%	23	1K	7.96 M	80.00	0.036	2.900	270Y	270.0 ± 15%	40	1K	0.796 M	5.00	1.100	0.440
4R7M	4.70 ± 20%	23	1K	7.96 M	70.00	0.040	2.700	331Y	330.0 ± 15%	40	1K	0.796 M	4.50	1.300	0.400
5R6M	5.60 ± 20%	23	1K	7.96 M	57.00	0.046	2.500	391Y	390.0 ± 15%	40	1K	0.796 M	4.20	1.400	0.380
6R8M	6.80 ± 20%	23	1K	7.96 M	38.00	0.050	2.300	471Y	470.0 ± 15%	40	1K	0.796 M	4.00	1.600	0.350
8R2M	8.20 ± 20%	23	1K	7.96 M	30.00	0.055	2.100	561Y	560.0 ± 15%	60	1K	0.796 M	3.20	2.700	0.280
100M	10.00 ± 20%	35	1K	2.520 M	29.00	0.080	1.800	681Y	680.0 ± 15%	60	1K	0.796 M	2.70	3.200	0.250
120M	12.00 ± 20%	35	1K	2.520 M	26.00	0.085	1.700	821Y	820.0 ± 15%	85	1K	0.796 M	2.60	3.500	0.230
150M	15.00 ± 20%	35	1K	2.520 M	29.00	0.100	1.600	102Y	1000.0 ± 15%	100	1K	0.252 M	2.30	4.00	0.220
180M	18.00 ± 20%	35	1K	2.520 M	22.00	0.110	1.500	122Y	1200.0 ± 15%	100	1K	0.252 M	2.30	4.40	0.200
220M	22.00 ± 20%	35	1K	2.520 M	19.00	0.130	1.400	152Y	1500.0 ± 15%	100	1K	0.252 M	2.00	5.20	0.180
270M	27.00 ± 20%	35	1K	2.520 M	17.00	0.140	1.300	182Y	1800.0 ± 15%	100	1K	0.252 M	1.70	7.00	0.170
330M	33.00 ± 20%	35	1K	2.520 M	15.00	0.150	1.200	222Y	2200.0 ± 15%	100	1K	0.252 M	1.50	8.50	0.160
390M	39.00 ± 20%	35	1K	2.520 M	14.00	0.160	1.100	272Y	2700.0 ± 15%	100	1K	0.252 M	1.40	9.20	0.140
470M	47.00 ± 20%	35	1K	2.520 M	12.00	0.180	1.000	332Y	3300.0 ± 15%	100	1K	0.252 M	1.30	11.0	0.120
560M	56.00 ± 20%	35	1K	2.520 M	12.00	0.300	0.930	392Y	3900.0 ± 15%	100	1K	0.252 M	1.20	16.0	0.110
680M	68.00 ± 20%	40	1K	2.520 M	9.00	0.350	0.850	472Y	4700.0 ± 15%	100	1K	0.252 M	1.00	19.0	0.100
820M	82.00 ± 20%	40	1K	2.520 M	8.00	0.370	0.780	562Y	5600.0 ± 15%	100	1K	0.252 M	0.90	21.0	0.090
101Y	100.0 ± 15%	40	1K	0.796 M	7.50	0.420	0.700	682Y	6800.0 ± 15%	100	1K	0.252 M	0.90	24.0	0.090
120Y	120.0 ± 15%	40	1K	0.796 M	7.00	0.480	0.650	822Y	8200.0 ± 15%	100	1K	0.252 M	0.80	31.0	0.080
150Y	150.0 ± 15%	40	1K	0.796 M	6.00	0.550	0.600	103Y	10000.0 ± 15%	100	1K	79.60 K	0.70	38.0	0.070
180Y	180.0 ± 15%	40	1K	0.796 M	5.50	0.820	0.520								

### TECHNICAL INFORMATION & PHYSICAL CHARACTERISTICS:



- Materials:
  1. Core: Ferrite DR Core & RI Core
  2. Wire: Enamelled Copper Wire
  3. Base: LCP E4008
  4. Terminal: Tinned Copper Plate
  5. Adhesive: Epoxy Resin
- General Specification:
  1. Storage Temperature: -40°C - +125°C
  2. Operation Temperature: -40°C - +105°C
  3. Rated Current: Base on Temperature & ΔL/L0A=10%max
  4. Resistance to solder heat: 260°C, 10 secs.

Note: All specifications subject to change without notice.